ABSTRACT

A system and method for manufacturing an integrated circuit packaging system includes: forming a base substrate including: providing a sacrificial carrier: mounting a metallic sheet on the sacrificial carrier, applying a top trace to the metallic sheet, forming a conductive stud on the top trace, forming a base encapsulation over the metallic sheet, the top trace, and the conductive stud, the top trace exposed from a top surface of the base encapsulation, and removing the sacrificial carrier and the metallic sheet; mounting an integrated circuit device on the base substrate; and encapsulating the integrated circuit device and the base substrate with a top encapsulation.

(Fig.1)